

# NAVOLCHI December

V. Calzadilla, M. Smit  
02/12/2013



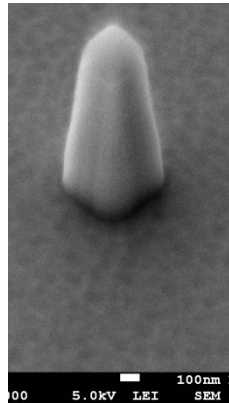
**TU** / **e**

Technische Universiteit  
**Eindhoven**  
University of Technology

**Where innovation starts**

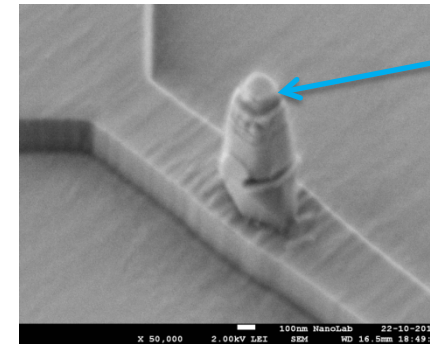
# Main fabrication issues in 1<sup>st</sup> run

- Non-vertical etch of bonded samples



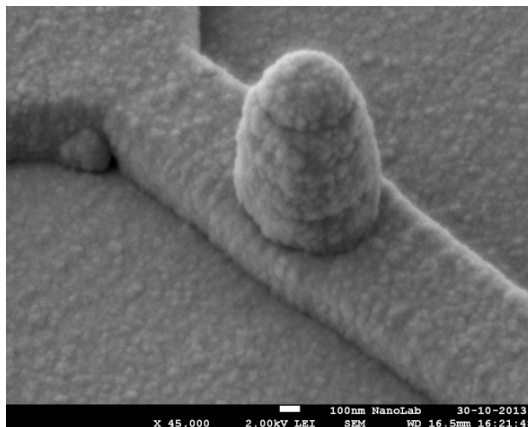
Sidewall slope ~ 5 degrees

- Unprotected pillar due to mask erosion

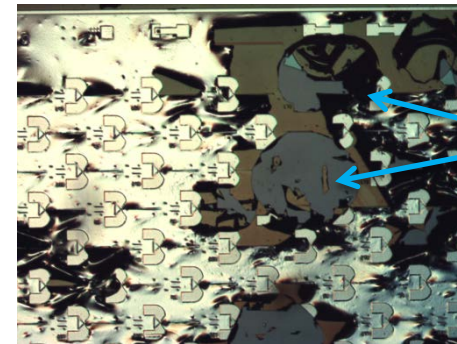


Top of pillar was etched

- Low quality of SiO<sub>2</sub>



- Outgasing (BCB?) during silver annealing (>400C)



Round defects

- Annealed silver was not etched with Degussa (KCN)

# Other issues

- Dicing of bonded samples
  - Could IMEC do dicing tests of bonded samples?
  - Shall I send my current sample to IMEC for dicing (as a test sample)?
- Meeting in Eindhoven, January 28
  - Confirm attendance. So far, from Doodle: 7 participants.
  - A list of hotels and a map to reach the campus/building will be sent.
  - Are you interested in a cleanroom tour?

